

Inhaltsverzeichnis

A1 Materialien (1)

Chair: Martin Schneider-Ramelow (Fraunhofer-Institut für Zuverlässigkeit und Mikrointegration IZM, Berlin)

- A1.1 Structural and electrical characterization of thin cerium-tin oxide heterolayers for hydrogen sensing 1**
 Carlos Alvarado Chavarin, Ioan Costina, Christian Wenger, Markus Ratzke, Carlos Morales Sanchez, Yuliia Kosto, Ingo Flege and Inga Fischer
- A1.2 Additive Fertigung von modifizierten SiCN-Keramiken hergestellt aus präkeramischen Polymeren..... 7**
 Afnan Qazzazie-Hauser, Kirsten Honnef und Thomas Hanemann
- A1.3 Konzepte zur Reduktion des MoS₂-Kontaktwiderstandes basierend auf großflächig gewachsenen PEALD-Filmen 11**
 Leander Willeke, Malte J. M. J. Becher, Nils Schmitt, Julia Jagosz, Andreas Ostendorf und Claudia Bock
- A1.4 PowderMEMS - Generic Integration of Functional Three-Dimensional Microstructures on Wafer Level..... 18**
 Björn Gojdka, Ole Behrmann, Mani Teja Bodduluri and Thomas Lisec

B1 Optische Komponenten (1)

Chair: Ulrike Wallrabe (Albert-Ludwigs-Universität Freiburg, Institut für Mikrosystemtechnik IMTEK)

- B1.1 KODIAK: Components and modules for improved optical diagnostics 26**
 Michael Scholles, Nicole Isserstedt-John, Martin Jahn, Dirk Kuhlmeier, Ana-Leonor Heitor Lopes, Martin Reuter, Benjamin Saft, Eric Schäfer, Mirjam Skadell and Alexander Zimmer
- B1.2 TiN-Si Schottky Diodes for SWIR Detection..... 30**
 Lion Augel, Hanying Wen and Jens Knobbe
- B1.3 Vektorieller Mikroscooperspiegel mit integrierter Positionssensorik zur schnellen Strahlpositionierung eines Therapielasers 35**
 Thilo Sandner, Thomas Graßhoff, Markus Schwarzenberg, Klemens Birnbaum, Tino Pügner und Jan Grahmann
- B1.4 Simulation und Charakterisierung von dielektrischen MEMS-Spaltwellenleitern für den THz-Bereich 42**
 Kristof Kother, Lisa Schmitt, Jan Barowski, Martin Hoffmann und Ilona Rolfes

C1 Health (1)

Chair: Jens Anders (Universität Stuttgart, Institut für Intelligente Sensorik und Theoretische Elektrotechnik)

- C1.1 Transparent microfluidic MEAs with organic electronic ion pumps for in vitro studies of the pathological retina..... 47**
 Roman Deubel, Lena Hegel, Josef Bolten, Andrea Kauth, Eashika Ghosh, Vivek Pachauri, Xuan Thang Vu, Sandra Johnen and Sven Ingebrandt

C1.2 Quantifizierung zirkulierender Tumorzellen aus Vollblut mittels Silizium-Mikrochips	51
Michael Knapp, Marvin Heyer, Matthias Ege, Samir Kadić, Astrid Lux, Franz Lärmer, Nils Paust, Roland Zengerle und Jochen Hoffmann	
C1.3 Self-Sensing of Piezoelectric Actuators: Integrated Bubble Detection for Reliable Drug Dosing	58
Kristjan Axelsson, Arham bin Tariq, Gabriel Zerbib, Martin Richter and Christoph Kutter	
C1.4 Improving Needle Insertion Accuracy with Multi-Local Impedance Sensors on a Needle	65
Jan Liu, Yongrok Jeong, Toni J. Ly, Ömer Atmaca, Inkyu Park and Peter P. Pott	

D1 Technologie in Anwendung

Chair: Amelie Hagelauer (Fraunhofer Research Institution for Microsystems and Solid State Technologies EMFT, München)

D1.1 Sensor for Thread Tension Measurement	70
Adrian Schwenck, Timo Weimer and Tobias Grözinger	
D1.2 Prädiktive Modelle für IR-Emitter in der miniaturisierten photoakustischen Gassensorik.....	74
Simon Essing, Gabriele Schrag, Tobias Mittereder und David Tumpold	
D1.3 Industrial Maskless Aligner: New levels of flexibility in lithography.....	78
Philip Paul and Daniel Braun	
D1.4 Photonischer Spektrumanalysator für Terahertz Quellen auf einem Chip oder im Wellenleiter.....	81
Benedikt Leander Krause, Amlan kusum Mukherjee und Sascha Preu	

P Postersession (1)

P1.A Mikrosysteme

Charakterisierung und Zuverlässigkeit von Mikrosystemen

P1.1A A novel method to characterize the correlation between gas diffusion and sodium contamination of anodic bonding	291
Yucheng Zhang, Dr. Francesco Solazzi, Dr. Michael Schiffer, Dr. Kai Schreiber, Dr. Norbert Cselyuszka, Dr. Nikolai Andrianov, Kurt Sorschag, Dr. Elmar Aschauer and Prof. Ing. Klaus-Dieter Lang	
P1.2A Evaluation of a modular microsystem structure for sensor-integrating machine elements...	227
Ilja Gomberg, Richard Breimann, Jan Küchenhof, Eckhard Kirchner, Dieter Krause and Hoc Khiem Trieu	
P1.3A Long-term and thermal shock stability of high-temperature pressure and force sensors	193
Muhannad Ghanam, Peter Woias and Frank Goldschmidtboeing	
P1.4A First Characterization of Comb Drive Based Micro Mirror Arrays.....	327
Mario Nitzsche, Anuroop Bajpai, Peter Dürr, Andreas Neudert and Anmona Shabnam Pranti	
P1.5A Efficient in-situ reliability monitoring of in-plane NED Bending Actuators during accelerated aging	525
Michael Stolz	

P1.6A Magnetische Streufeld-basierte 2D-Rotationsbestimmung für einen Mikroaktor mit großer Auslenkung	124
Mario Farny, Michael Olbrich, Arwed Schütz, Christoph Ament, Tamara Bechtold und Martin Hoffmann	
P1.7A In-situ SEM Analysis Tool for Stretchable Metal-Elastomer-Laminate-Membranes for Flexible Sensors	216
Benjamin Sittkus, Gerald Urban and Ulrich Mescheder	
P1.8A Manufacture and application of a sensor inlet for high-temperature measurements in the frictional zone of an extrusion die	672
Selina Raumel, Amirreza Moradi and Marc C. Wurz	
P1.9A Smart Micro Systems - The key to get a digital twin of a real high-tech fab	
Jorge M Monsalve, Bert Kaiser, Harald Schenk (Fraunhofer IPMS, Germany)	
P1.10A Influence of different ketones on the spectra of a MEMS FAIMS-chip.....	750
Nils Funke, Alexander Graf, Olaf R. Hild, Jessy Schönfelder and Michael Scholles	
P1.11A Concept for a MEMS-based GC Chip as a Part of an Easy-to-Use Handheld System	536
Alexander Graf, Olaf R. Hild, Gina Zeh, Tilman Sauerwald and Mark Bücking	
P1.12A A microfluidic-chip-based system for the determination of nutrient ion concentrations in hydroponic solutions by means of ion-selective electrodes (ISEs).....	723
Thomas Klotzbücher, Mathis Komorek, Juri Magomajew and Rainer Gransee	
P1.13A Kompakter Nanoindenter mit integrierten Weg- und Kraftsensoren.....	259
Thomas Frank, Stefan Hermann, André Grün, Danny Hanig, Manuel Kermann, Heike Wünscher, Georg Font und Luca Zenone	
P1.14A CyBarKeeper: Design and implementation of a high-resolution haptic sensor system for a robotic gripper using embedded machine learning algorithms.....	181
Daniel Rossbach, Daniel Konegen, Marcus Rüb, Alexander Willmann, Markus Kuderer, Hansjörg Rietsche and Oliver Amft	
P1.15A Manufacturing of a Reluctance Actuator for Use as a Hearing Implant in the Middle Ear ...	89
Eileen Müller, Marco Adamscheck, Eike C. Fischer, Anatoly Glukhovskoy, Maren S. Prediger, Folke Dencker and Marc C. Wurz	
P1.16A Entwicklung von piezoelektrisch betriebenen quasi-statischen 2D MEMS-Spiegeln mit extrem hohem FoV für scanning LiDAR.....	580
Paul Raschdorf, Jeong-Yeon Hwang, Lena Wysocki, Lianzhi Wen, Jörg Albers, Gunnar Wille, Erdem Yazar und Shanshan Gu-Stoppel	
P1.17A Surface photovoltage spectroscopy for the evaluation of oxidation processes in the microelectronic industry	655
Vladimir Kolkovsky	
P1.18A Accuracies/Repeatabilities of Airborne (C)MUT Characterization.....	667
Sören Köble and Sandro G. Koch	
P1.19A Ein kostengünstiges, tragbares Open-Source-Sensorboard mit drahtloser Kommunikation und Fluoreszenzdetektion zur farbmetrischen Detektion für mikrofluidische Anwendungen	237
Yushen Zhang, Tsun-Ming Tseng und Ulf Schlichtmann	

P1.20A Gleichzeitige Extraktion von extrazellulären Vesikeln und zellfreier DNA aus einer einzigen Blutprobe durch zentrifugale Mikrofluidik.....	631
Ehsan Mahmodi Arjmand, Franziska Schlenker, Gustav Grether, Truong-Tu Truong, Tobias Hutzenlaub, Roland Zengerle, Nils Paust, Jan Lüddecke und Peter Juelg	
P1.21A Solving Partial Differential Equations with Monte Carlo / Random Walk on an Analog-Digital Hybrid Computer	556
Dirk Killat, Sven Köppel, Bernd Ulmann and Lucas Wetzel	
P1.22A Design of Micromachined Ultrasonic Transducers for Variability with the Sample-Average Approximation Method	639
Jorge M. Monsalve, Bert Kaiser and Harald Schenk	
P1.23A Bistable Actuation Based on TiNiHf/Si Shape Memory Nanoactuators	93
Zixiong Li, Gowtham Arivanandhan, Sabrina M. Curtis, Eckhard Quandt and Manfred Kohl	
P1.24A Overcoming Thermoviscous Effects: Design and Fabrication of Microacoustic Metagratings for Anomalous Refraction at Ultra-High Frequencie.....	676
Anton Melnikov, Sören Köble, Severin Schweiger, Yan Kei Chiang, Steffen Marburg and David A. Powell	
P1.25A Numerical study of geometry variations in a balanced MEMS loudspeaker.....	651
Franziska Wall, Sergiu Langa, Hermann A. G. Schenk, Anton Melnikov, Jorge M. Monsalve and Bert Kaiser	
P1.26A Elektrische Spin-Injektion in kantenemittierenden Halbleiterlasern.....	108
Natalie Jung, Markus Lindemann, Julian Ritzmann, Samira Webers, Arne Ludwig, Andreas Wieck, Soma Salamon, Heiko Wende, Nils C. Gerhardt und Martin R. Hofmann	
P1.27A Surface Passivated Porous Silicon-Based Antireflective Coating.....	634
Shervin Keshavarz, Andras Kovacs and Ullrich Mescheder	
P1.28A Micro-Fabrication Techniques and Materials for Advanced MEMS Energy Harvesting	
Torben Dankwort, Minhaz Ahmed, Niels Clausen and Björn Gojdka	
P1.29A Zero-Power Wake-up for Event-Triggered Ocean Wave Monitoring	
Minhaz Ahmed, Torben Dankwort, Linda Nolte, Anmol Khare, Sven Gruenzig and Björn Gojdka	
P1.30A Efficient Wireless Power Transfer System for a Moving Receiver.....	517
Miguel Angel Rodriguez Carrillo, Simon Mill, Bernhard Birkmann, Gerold Menz and Ulrike Wallrabe	
P1.31A Impact of bandwidth and number of measurement points on Q-factor measurement precision in piezoelectric MEMS resonators	681
Michael Schneider and Ulrich Schmid	
P1. 32A RFID Sensortransponder mit antiferroelektrischen, eingebetteten Dünnschichtkondensatoren	881
Andreas Heinig, Alison E. Viegas, Andreas Weder and Malte Czernohorsky	

P Postersession (1)

P1.B Materialien, AVT & Simulation

Materialien

- P1.1B Piezoelektrische MEMS-Aktuatoren basierend auf ferroelektrischen Aluminium-Scandium-Nitrid Doppellagen..... 129**
Tom-Niklas Kreutzer, Fabian Stoppel, Simon Fichtner, Muhammad Zubair Ghorri and Fabian Lofink
- P1.2B PECVD grown Graphene based Carbon Nanostructures for Electrochemical CO2 Reduction and Gas Sensing Applications 302**
Tobias Schwarz, Tobias Weidauer, Trung Tran, Corinna Kaulen, Alfred Lechner and Martin Kammler
- P1.3B Highly Conductive Thermally Reduced Graphene Oxide Films via Transition Metal Catalyzed Graphitization..... 605**
Leonhard Niemann, Markus Gruschwitz, Gabriel Sellge, Martin Köhne, Olav Hellwig and Christoph Tegenkamp
- P1.4B Thermal annealing of Nb2O5 and Ta2O5 thin films for CMOS based chemical sensors..... 609**
Falah Al-Falahi, Christopher Beale, Eberhard Kurth, Peter Reinig2 and Olaf R. Hild
- P1.5B Defect density investigations on Ta2O5 films deposited by Atomic Layer Deposition..... 706**
Schabnam Noghabai and Hoc Khiem Trieu (*Abstract only*)
- P1.6B Energy dispersive X-ray spectroscopy and spectroscopic ellipsometry for the investigation of ScAlN for applications in microsystems technology..... 276**
Rebecca Petrich, Hauke Honig, Younes Slimi, Lorenz Steinacker, Stephan Barth, Hagen Bartzsch, Daniel Glöß, Raphael Kuhnen, Dietmar Frühauf, Peter Schaaf, Stefan Krischok and Katja Tonisch
- P1.7B Sputtered TiAl-Monolayers: Optimization of Thickness Uniformity and Stress over Target Lifetime 247**
Stephanie Weller, Sebastian Döring, Erik Schumann and Ghislain Ntokap Nguemegne
- P1.8B Ion beam technology for thin piezoelectric films 868**
Matthias Nestler and Andrea Schulze
- P1.9B Fabrication and characterization of suspended SiNx islands for measurement of thermal and thermoelectric properties of micropatterned materials..... 767**
Felix Jiang, Guangzhen Xie, Sven Ingebrandt and Xuan Thang Vu

AVT

- P1.10B Herstellung hauchdünner, bleifreier Bariumtitanat-Piezokeramik mittels Inkjet Printing .. 136**
Ines Ketterer, Cheng-Kang Yang, Emine Cimen und Matthias Wapler
- P1.11B Thin Film Under Bump Metallization for Wafer Level Packaging 254**
Roy Knechtel, Martin Seyring, Micaela Wenig, Manuela Göbelt, Dominik Thiedke and Volker Götz
- P1.12B Niedrigausdehnende Gläser für mikromechanische Anwendungen 616**
Christoph Weigel, Valeriya Cherkasova, Mathias Holz, Thomas Fröhlich and Steffen Strehle

P1.13B Laser-assisted bonding between silicon and glass for the production of hermetic packages.....	332
Jannik Koch, Levin M. Brinkmann, Alexander Kassner, Folke Dencker and Marc C. Wurz	
P1.14B Integration of film-based sensor technology in additively manufactured components	154
Robin G. Basten, Sebastian Bengsch and Marc C. Wurzl	
P1.15B Reactive bonding of an integrated CMOS strain sensor to steel by using hard and soft solders.....	197
Axel Schumacher, Peter Meyer, Georg Buschbeck, Erik Pflug, Julius Böttcher, Stephan Knappmann, Thorsten Hehn and Alfons Dehé	
P1.16B PCB-printing and assembly with a multi-tool industrial six-axis robot.....	568
Thomas M. Wendt, Aron Wiesner, Philipp Gawron and Lukas Stiglmeier	
P1.17B Place and bend assembly of photonic modules.....	121
Heinrich Grüger, Jens Knobbe, Sandro G. Koch, Marlon Schulz, Sebastian Sdrenka and Gerhard Ziegmann ³	
P1.18B Herstellung zuverlässiger elektrischer und optischer Verbindungen für Siliziumnitrid-Photonik mittels Thermokompressionsbonden	729
Matin Blasl, Maysam Namdari, Juliane Fröhlich und Hermann Oppermann	
Sonstige Aspekte von Mikrosystemen	
P1.19B Festkörperkühlung mittels elastokalendarischem Effekt auf Basis von Elastomeren und dehnungsinduzierter Kristallisation	
Jan Leutner, Carina Stephanie Ludwig und Jürgen Rühle	
P1.20B 3D printed NMR compatible ceramic bioreactor	
Julia B. Schulte-Hermann, Monsur Islam, Jan Gerrit Korvink and Neil MacKinnon	
P1.21B Characterization of TEOS-based SiO₂ for integrated photonics.....	314
Matthias L. Vermeer, Hoc Khiem Trieu and Timo Lipka	
P1.22B Hardware Implementation of Reflective Intelligent Surfaces for 6G communication networks	222
Robert Stöcker, Julia-Marie Köszegi, Michael Kaise and Ivan Ndip	
P1.12B Manufacturing of dielectric elastomer transducers using 3D printing	284
Andreas Hubracht and Jürgen Maas	
P1.24B Laser-Assisted Positioning for Vertical Pull-Off Tests.....	591
Nicolai Simon, Nico Hofmann, Chi-Nghia Ho and Volker Bucher	
P1.25B Modular and compact interferometric fiber optic gyroscope configuration for high precision rotary motion	172
Christian Janeczka, Moritz von Ravenstein, A. Al-Shami, Vanessa Zamora and Henning Schröder	
P1.26B Gecko-Effekt: Die neue Art der Mikromontage	871
Yolanda Stabel (INNOCISE GmbH, Germany); Stefan John (INNOCISE GmbH, Germany)	
P1.27B Development of aShielding Box for Through-Facade Coupler (TFC) Evaluation.....	739
Alireza Jahanbakhshi, Zhenming Tian, Thomas Bolz, Peter Hildenhagen, Daniel Erni and Andreas Rennings	

A3 Materialien (2)

Chair: Andreas Mai (Leibniz Institut für innovative Mikroelektronik IHP, Frankfurt/ Oder)

- A3.1 Sputtered FeCoB Soft Magnetic Thin Films for Surface Acoustic Wave Sensors 341**
 Jana Marie Meyer, Muhammad Zubair Ghori, Matthias Rickers, Simon Fichtner, Mani Teja Bodduluri, Lars Blohm, Erdem Yazar, Thorsten Giese and Fabian Lofink
- A3.2 Großflächiges polykristallines Wachstum von Molybdändisulfid auf 200 mm Glaswafern für die Integration in einem 2D pH-Sensorsystem..... 345**
 Julia Jagosz, Leander Willeke, Malte Becher, Andreas Ostendorf und Claudia Bock
- A3.3 Additive Fertigung von Ti6Al4V-Bauteilen für Anwendungen in der Medizintechnik..... 351**
 T. Hanemann, S. Antusch, D. Nötzel und R. Eickhoff
- A3.4 Membranlose Drucksensoren für den Einsatzbereich über 1000 MPa 357**
 Thomas Frank, Stefan Hermann, André Grün, Danny Hanig, Manuel Kermann, Michael Hintz und Andrea Cyriax

B3 Optische Komponenten (2)

Chair: Harald Schenk (Fraunhofer-Institut für Photonische Mikrosysteme IPMS, Dresden)

- B3.1 Optical dew point sensor with integrated primary electronics based on silicon-ceramic composite technology..... 361**
 Thomas Handtea, Boris Goj, Lars Dittrich, Peter Keil and Stefan Sinzinger
- B3.2 Towards Integrated Tamm Plasmon-Polariton Thermal Emitters..... 864**
 Gerald Pühringer and Bernhard Jakoby
- B3.3 Design and fabrication of a metalens for shaping the light of quantum dot based light emitting diodes 365**
 Toni D. Großmann, Martin Möbius, Susanne Hartmann, Christoph Robert Meinecke, Jörg Martin Danny Reuter and Harald Kuhn
- B3.4 OLED-on-Silicon for microdisplays in near-to-eye applications and optoelectronic sensing ... 371**
 Philipp Wartenberg, Bernd Richter, Judith Baumgarten, Andreas Fritscher, Stephan Brenner, Simone Lenk, Steffen Damnik, Martin Rolle, Johannes Zeltner, Christian Schmidt, Josephine Mütze, Dirk Schlebusch, Karsten Fehse, Michael Törker, Steffen Damnik, Florian Schuster and Uwe Vogel

C2 Health (2)

Chairs: Michael Scholles (Fraunhofer-Institut für Photonische Mikrosysteme IPMS, Erfurt)

- C2.1 Sprunggelenk-Orthese mit textilbasiertem Fehlbelastungssensor**
 Kay Ullrich
- C2.2 Novel Smart Sensor Integration for Size- and Power-Constrained Wearable and Hearable Applications..... 375**
 Timo Giesselmann and Ivan Flores Delgado
- C2.3 Wearable Smart Patch Sensors for Monitoring Knee Laxity..... 103**
 Karthika Sheeja Prakash, Vicky Chantal von Einem, Sabari Kannan Muthulagu, Priyank Agarwal, Peter Woias und Laura Maria Comella

C2.4 Laser-Induced Structuring of Glass as a Promising Manufacturing Technology for Lab-on-Chip Devices: Opportunities and Challenges	382
Werner J. Karl, Nagashree B. Jagadesh and Roy Knechtel	

A4 Messtechnik

Chair: Gerhard Kahmen (IHP GmbH, Frankfurt/ Oder)

A4.1 Mikromechanische Zugversuche auf Chip-Level.....	389
Philip Schmitt, Maira Buschheuer und Martin Hoffmann	
A4.2 Automatic wafer probing of photonic integrated circuits with thermal tuning and permanent trimming functions	393
Timo Lipka, Matthias L. Vermeer, Lukas Rennpferdt, Nadeem K. Alhareeb, I. Gomberg, and Hoc Khiem Trieu	
A4.3 Application of Mathematical Inverse Analysis in MEMS Testing.....	397
Jürgen Müller, Monika Heringhaus, Dominik Messner and Thomas Northemann	
A4.4 Correlative surface characterization of micro-electro-mechanical-systems.....	401
Maximilian H. Kabbe, Jan G. Korvink, Richard Thelen and Jürgen J. Brandner	

B4 Quantentechnologien

Chair: Wenke Weinreich (Fraunhofer-Institut für Photonische Mikrosysteme IPMS, CNT, Dresden)

B4.1 Challenges of scaled quantum computing system and the opportunities of Microelectronics	
Benjamin Lilienthal-Uhlig	
B4.2 Design and evaluation of a discrete assembled frontend for an industrial quantum sensor.....	408
Albert Dorneich, Christoph Boeckenhoff and Nick Hof	
B4.3 Nanosized vacuum gap electromechanical devices with integrated piezoelectric actuator	413
Ioan Ignat, Elisabet Arvidsson, August Roos, Ermes Scarano, David Haviland, Daniel Platz and Ulrich Schmid	
B4.4 Quanten-Magnetometer mit höchster Empfindlichkeit für planetare Explorationen	
André Kretschmann	

C4 Integrationstechnologien

Chair: Manuela Junghänel (Fraunhofer IZM-ASSID, Moritzburg)

C4.1 Integration eines ferroelektrischen Speichermoduls in das BEoL der XFAB XT018 Technologie zur Realisierung von 1T1C-FeFETs	417
David Lehninger, Konrad Seidel, Ayse Sünbül, Thomas Kämpfe, Fred Schöne, Hannes Mähne, Kerstin Bernert, Steffen Thiem und Maximilian Lederer	
C4.2 Eine interaktive Design-Plattform für 3D-gedruckte mehrlagige Mikrofluidikchips mit Design-for-Manufacturing-Funktion.....	425
Yushen Zhang, Tsun-Ming Tseng und Ulf Schlichtmann	
C4.3 Towards Heterogeneous Integration of InP on Si via Micro Transfer Printing by direct adhesion	430
Ketan Anand, Patrick Steglich, Jochen Kreissl, Lars Zimmermann and Andreas Mai	

C4.4 Ceramic Multilayer Technology as Integration Platform and Interposer Technology	436
A.Goldberg, S. Ziesche, M. Ihle, P. Pandey, B. Manhica, K. Reinhardt and S. Körner	
A5 Prozesstechnologien (1)	
Chair: Joachim Burghartz (Institut für Mikroelektronik Stuttgart)	
A5.1 Three-dimensional folded MEMS manufacturing for an efficient use of area.....	307
Dennis Becker, Achim Bittner and Alfons Dehé	
A5.2 Modelling and process development of ceramic heat transfer layers for ignition of integrated reactive multilayer systems.....	441
Klaus Vogel, Sebastian Schermer, Christian Helke, Sven Zimmermann and Danny Reuter	
A5.3 Passive micro check valves in glass manufactured by selective laser etching.....	445
Sven Bohne, Sibashish Laha and Hoc Khiem Trieu	
A5.4 Reaktives Ionenätzen von Silikatgläsern für optische Mikrosysteme.....	449
Christoph Weigel, Ulrike Brokmann, Meike Hofmann, Arne Behrens, Edda Rädlein, Martin Hoffmann, Stefan Sinzinger und Steffen Strehle	
A5.5 Fabrication of IC substrates utilizing semi-additive copper deposition and a machine-optimized anode control system	851
Ruben Kahle, Michael Gerberich and Andreas Ostmann	
B5 Sensorik (1)	
Chairs: Anton Grabmaier (Fraunhofer-Institut für Mikroelektronische Schaltungen und Systeme IMS, Duisburg)	
B5.1 Demonstration of wafer-level integrated permanent bias micromagnets for magnetic field sensors.....	452
Florian Ziegler, Markus Stahl-Offergeld, Dominik Schröder, Niels Clausen, Christian Hedayat, Hans-Peter Hohe, Thomas Lisec and Björn Gojdka	
B5.2 Fluid-independent flow sensor using a combination of thermal flow sensor and vibronic density sensor	457
Christof Huber, Ralf Bernhardsgrütter, Jürgen Dorsch, Marcel Giger, Fabio Schraner, Sandro Schab and Christoph Hepp	
B5.3 Manufacturing and Characterization of Piezoelectric Force SensorArrays for Investigation of Ultrasonic Wire Bonding.....	462
Matthias Arndt, Yangyang Long, Chengyan Hu, Folke Dencker, Jens Twiefel and Marc Christopher Wurz	
B5.4 Eine minimalinvasive Blatt-Küvette für VOC-Messungen an Buchen.....	466
Yasmina Frey, Simon Haberstroh, Christiane Werner und Ulrike Wallrabe	
B5.5 Herstellung ko-resonant gekoppelter Cantilever-Sensoren mit geometrischer Frequenzanpassung	470
Ioannis Lampouras und Julia Körner	

C5 Aufbau- und Verbindungstechnik

Chair: Karl-Heinz Bock (Technische Universität Dresden)

C5.1 Enhancing the 3D Patterning of MEMS – An Extended Toolbox	754
Lukas Rennpferdt, Sven Bohne and Hoc Khiem Trieu	
C5.2 Challenges in Realizing Silver Sintered Flip-Chip Interconnects for High Temperature Sensor Systems.....	473
Olaf Rämmer, Constanze Weber, Matthias Hutter, Malte Spanier, Andreas Ostmann and Martin Schneider-Ramelow	
C5.3 Innovative Fabrication of Polymer-Based Sensor Systems by Flip-Chip Integration of Ultrathin Chips Using Nanowires for Medical Applications	480
Ulrike Passlack, Björn Albrecht, Christine Harendt, Florian Weißenborn, Sebastian Quednau and Joachim N. Burghartz	
C5.4 Hermetic packaging for photonic integrated circuits on glass interposers	483
Daniel Weber, Kevin Kröhnert, Oliver Kirsch, Niklas Schöning, Norbert Ambrosius, Henning Schröder, Michael Schiffer and Martin Schneider-Ramelow	
C5.5 Technische Machbarkeitsstudie zur Massiv-Parallelen Montage und Verbindung von Mikro-LEDs	490
Charles-Alix Manier, Kai Zoschke und Hermann Oppermann	

D5 Simulation & Modelling

Chair: Jan Mehner (Technische Universität Chemnitz)

D5.1 Simulation von Dämpfungseffekten in unregelmäßig perforierten MEMS Bauteilen durch Kompaktmodelle.....	499
Friederike Michael und Gabriele Schrag	
D5.2 Simulation-based Design of a Magnetostrictive Middle Ear Actuator	503
Marco Adamscheck, Eike Fischer, Eileen Müller, Anatoly Glukhovskoy, Maren S. Prediger, Folke Dencker and Marc C. Wurz	
D5.3 Design and Optimization of Piezoelectric MEMS Resonator Electrodes using Finite Element Methods and Image Processing	509
Ananya Srivastava, Achim Bittner and Alfons Dehé	
D5.4 Design and Analysis of a Mechanical XOR Gate Based Zero Power Device.....	513
Kar Jing Yap, S. Bohne and H. K. Trieu	
D5.5 ZuSE-KI-mobil: Platform for Energy Efficient AI-Processors in Mobile Applications.....	889
Hans-Jörg Vögel, Jürgen Becker, Jens Benndorf, Kay Bierzynski, Holger Blume, Gerhard Fettweis, Martin Friedrich, Simon Friedrich, Darius Grantz, Julian Höfer, Fabian Kempf, Matthias Lüders and Gerd Teepe	

P Postersession (2)

P2.A Modellierung und Simulation

- P2.1A Efficiently modelling the fluid-structure interaction of micro-plateresonators with viscous fluids using modal basis functions** 98
Andre Gesing, Thomas Tran, Daniel Platz and Ulrich Schmid
- P2.2A Hydrogen Release from PECVD Thin Films in MEMS Cavities**..... 162
Prafullkrishna Kiran Dani, Jochen Franz and Joachim Knoch
- P2.3A An Enhancement of the Unscented Transform for Efficiently Estimating Statistical Measures and Sensitivity Indices** 264
Kevin Marolt, Michael Sautter and Thomas Northemann
- P2.4A Nonlinear Model Order Reduction of a MEMS Actuator by a Trajectory Piecewise-Linear Approximation**..... 551
Arwed Schütz, Sönke Maeter and Tamara Bechtold
- P2.5A Evaluation of Mixing Performance of a Coaxial Lamination Mixer for Prediction of Properties of Lipid Nanoparticles From Antisolvent Precipitation** 665
Songtao Cai, Peer Erfle and Andreas Dietzel
- P2.6A Solving Partial Differential Equations with Monte Carlo / Random Walk on an Analog-Digital Hybrid Computer** 556
Dirk Killat, Sven Köppel, Bernd Ulmann and Lucas Wetzel
- P2.7A Simulation and evaluation of resonant magnetoelectric sensors based on TiN/AlN/Ni thin films**..... 144
Rebecca Petrich, Simeon Katzer, Bernd Hähnlein, Maximilian Krey, Hannes Töpfer, Stefan Krischok, Raphael Kuhnen, Dietmar Frühauf and Katja Tonisch
- P2.8A Implantable Thermoelectric Generator with High Aspect Ratio Thermolegs and Integrated Voltage Converter** 243
Yongchen Rao, Matthias Voss, Tamara Bechtold and Dennis Hohlfeld
- P2.9A Investigation on MEMS Designs of Noncontact Varactors for high Tuning Ratios** 848
Klaus Schimmanz
- P2.10A 3D FEM simulation of stress evolution induced during sintering in silicon-ceramic composite substrates**..... 876
Parastoo Salimitari, Steffen Strehle and Sarah Günther-Müller (Technische Universität Ilmenau, Germany)

P Postersession (2)

P2.B Integrations- und Prozesstechnologien

Prozesstechnologien

- P2.1B Sensor Tag in Chip-Film Patch Technology**..... 211
M. Kübler, S. Epple, U. Passlack, B. Albrecht, C. Harendt und J. N. Burghartz
- P2.2B Fabrication Method and Characterization of Molded Interconnect Device Micro Transformer in Planar Form by Embedding Sintered Ferrite Cores** 599
Tim N. Bierwirth, Eike C. Fischer, Maren S. Prediger, Trong M. Le, Folke Dencker and Marc C. Wurz

P2.3B on-CMOS-Integration of Spatial Light Modulator for Holographic MR/AR Applications ..	700
Sebastian Döring, Patrick Recknagel, Christoph Hohle and Peter Dürr	
P2.4B On-Chip-Brechungsindexsensoren auf der Grundlage plasmonischer TiNNanoloeh-Arrays.....	336
Akant Sengül, Sebastian Reiter, Weijia Han, Christian Mai, Davide Spirito, Josmy Jose, Oksana Fursenko, Christian Wenger und Inga A. Fischer	
P2.5B Submicron alignment accuracy of frontside to backside lithography for MEMS applications	645
Sergiu Langa, Marco Urban, Andreas Herrmann, Erik Schumann, Albrecht Kleye, Jorge Mario Monsalve Guaracao, Maximilian Wagner and Bert Kaiser	
P2.7B Tuning der Schwellspannung und Kanalmobilität von Galliumnitrid- MOSFETs mittels Abscheidetemperatur des Gate-Dielektrikums.....	202
Mirjam Henn und Christian Huber	
P2.8B Optimization of the etching process for improved DNA immobilization on Parylene	
Susanne Hartmann, Thomas Werner, Julia Hann, Christian Helke, Micha Haase, Christoph R. Meinecke and Danny Reuter	
P2.9B Microtechnological Production of Integrated Optical Gratings Using Laser Beam Lithography for Atomic Interferometers.....	577
Sascha de Wall, Alexander Kassner, Folke Dencker and Marc Christopher Wurz	
P2.10B Environmentally friendly cleaning of microsystem products in the medical industry and photovoltaics.....	722
Günther Schmauz	
Integrationstechnologien	
P2.11B Monolithic integration of permanent magnets in SOI-based micro-mechanisms	272
Philip Schmitt, Björn Gojdka, Thomas Lisec, Florian Ziegler, Frederico Orlandini-Keller, Thibaut Devillers, Nora M. Dempsey and Martin Hoffmann	
P2.12B Liquid Cooling of PCB-Assembled CMOS Biosensor Arrays.....	663
Timo Lausen, Mohamad Al Ashrafani and Roland Thewes	
P2.13B Recovery Methods of Gallium Nitride Plasma Etch Damage.....	648
Tobias Claus, Stefan Regensburger and Tobias Erlbacher	
P2.14B Double-sided measurement of defect density on through-structured wafers before wafer level bonding	710
Sergiu Langa, Kirstin Bornhorst, Marco Urban, Michael Scharnweber, Wolfgang Doleschal, Andreas Rieck, Christian Tille, Juliane Weise and Bert Kaiser	
P2.15B Development and Characterization of transferable Thin Film Sensor Technology on Carbon Fibre reinforced Plastics.....	113
Steffen Haderler, Fabian Vogt and Marc Christopher Wurz	
P2.16B Electric-Field-Assisted Printing Technology for Enhanced Patterning of Micro- and Nanostructures.....	205
Nadine Philippin, Ingo Kuehne and Gabriele Schrag	

P2.17B Improving the recyclability of printed electronics.....	300
Florian Janek, Yannic Brasse, Tobias Kraus, Carl Emmerechts, Jean-Michel Clanet, Benoit Grymonprez, Tobias Grözinger, Kerstin Gläser	
P2.18B Optimized quality and process control through AI-based image classification at Fraunhofer IPMS	311
Michael Meinel, Juliane Weise and Ines Thurner	
P2.19B Zwei-Photonen Polymerisation mittels monolithisch modenkoppelnden Diodenlasern	521
Nils Surkamp, Felix Behlau, Wangyang Zhong, Shulin Wohlfeil, Andrea Knigge, Cemal Esen und Martin R. Hofmann	
P2.20B Setup of an ultra-high vacuum bonder for the encapsulation of quantum systems.....	763
Niklas Droese, Julian Petring, Steffen Hadel, Alexander Kassner, Folke Dencker and Marc C. Wurz	
 P Postersession (2)	
P2.C Wirtschaft und Arbeit	
P2.1C Implementation of a hand gesture recognition using ultrasound measurements on a NVIDIA Jetson platform with AI-based evaluation	694
Marcel Jongmanns	
P2.2C The ForTune Toolbox: Building Solutions for Condition-Based and Predictive Maintenance Focusing on Retrofitting.....	541
Maryam Assafo, Martin Lautsch, Priscile Suawa, Marcel.Jongmanns, Michael Huebner, Marc Reichenbach, Carsten Brockmann, Denis Reinhardt and Peter Langendoerfer	
P2.3C Design of an energy-autonomous sensor with wireless data data transmission for use on rollers.....	166
Andreas Bürger, Sylvio Simon and Stephan HERNSCHIER	
P2.4C Structural Integration of Smart Sensors for the Industrial Internet of Things	185
Volkhard Beyer, Dirk Mayer, Frank Haiduk, Marco Meinig, Steffen Wittemeier, Volker Geneiß, Philipp Meißner, Andreas Weder, Thomas Werner, Wolfram Steller and Wolfgang Zorn	
P2.5C Big Data Analytics as a step-change for MEMS Development and Manufacturing.....	586
Katharina Bierwagen, Carsten Klein, Akshay Markanday, Markus Braun and Monika Heringhaus	
P2.6C Entwicklung einer KI-basierten Prozessoptimierung in einer vertrauenswürdigen verteilten Fertigung über die gesamte Prozesskette	624
S. Voges, K.-F. Becker, P. Fruehauf, M. Heimann, S. Nerreter, R. Blank, M. Erdmann, S. Gottwald, A. Hofmeister, P. Lopuszanski, M. Hesse, M. Thies, S. Mehrafsun, R. Fust, E. Beck, M. Becicka, J. Pawlikowski, B. Schröder, C. Voigt, T. Braun und M. Schneider-Ramelow	
 P Postersession (2)	
P2.D Gesundheit und Pflege	
P2.1D Design of an optically pumped magnetometer based on hot atomic vapor targeted at medical diagnostics.....	117
Philipp Neufeld, Janine Riedrich-Möller, Tino Fuchs, Arne Wickenbrock, and Dmitry Budker	

P2.2D Coplanar Si architecture for chemiresistive hydrogen gas sensor	295
Karanvir Singh, Ashutosh Sharma, Dario Mager, Jan G. Korvink and Bharat Sharma	
P2.3D Finger position sensing on curved surfaces in braille displays.....	140
H. Alaboz, B. Sittkus, D. Muley and U. Mescheder	
P2.4D Real-time Dynamic Light Scattering of Nanoparticles for Analysis in Microfluidic Systems	152
Cornelius S. Bausch, Ebrahim TaiediNejad, Jörn Wittek, Andreas Dietzel and Michael Baßler	
P2.5D Bovine Oocyte Characterization by Microfluidic Aspiration-Assisted Electrical Impedance Spectroscopy	691
Yuan Cao, Ann-Selina Fries, Olav Granacher, Julia Floehr, Christine Wrenzycki and Uwe Schnakenberg	
P2.6D Energy Requirement and Energy Management for an Active Implant	319
Sonja Müller and Ulrich Mescheder	

P Postersession (2)

P2.E Kommunikation & Sicherheit

P2.1E Ultrasonic Energy Harvesting and Communication ASIC for Sensor- Integrated Machine Elements	734
Dominic Korner, David Riehl and Klaus Hofmann	
P2.2E Integration of LTCC into Printed Circuit Boards for Trustworthy Electronics	177
Annett Schroeter, Uwe Krieger, Christoph Lehnberger, Peter Uhlig and Adrian Goldberg4	
P2.2E Inductive sensor with integrated components	619
Dincer Sirkeci and Uwe Maaß	

P Postersession (2)

P2.F Mobilität

P2.1F Vergleich verschiedener Antriebskonzepte für MEMS-Aktoren	547
Stefan Bedacht	
P2.2F Silver and Silver-Copper mixed pastes for application in die- and substrate attach.....	571
Adrian Stelzer and Dr. Battist Rábay	

P Postersession (2)

P2.G Nachhaltigkeit, Energie und Klima

P2.1G Mikromechanische Konstantkraft-Mechanismen.....	529
Anna Christina Thewes und Martin Hoffmann	
P2.2G Verwendung von Siliziumdehnungssensoren für makroskopische Prüfkörper	132
Thomas Frank, Stefan Hermann, André Grün, Danny Hanig, Manuel Kermann, Michael Hintz, Andrea Cyriax und Ralf Röder	

P2.3G	Life cycle assessment of a sensor system for cognitive robots	615
	Priya Sharma, Martin Zumpe, Maximilian Stange and Ibrahim Al Naser	
P2.4G	Ein drahtloser Sensorknoten für die gleichzeitige Messung der photosynthetisch aktiven Strahlung (PAR) und des Blattflächenindex (LAI)	595
	Johannes Klüppe, Peter Woias und Laura Maria Comella	
P2.5G	Digital Microfluidics for the Investigation of Reaction Kinetics at Liquid-Liquid Interfaces	686
	Jan Wagner, Oliver Fiukowski, Andrij Pich, and Uwe Schnakenberg	
P2.6G	Tiny Machine Learning Sensor Platform for Local Sensor Data Fusion and Evaluation	714
	Florens Fraidling, Christian Hochreiter, Ferdinand Heinrich, Florian Rieger and Franz Wenninger	
P2.7G	Wrinkle-free bonding of thin membranes in a microfluidic bioreactor	233
	Leona M. Schmidt-Speicher, Christian Metzger, Ralf Ahrens, Dario Mager, Andreas E. Guber and Jan G. Korvink	
P2.8G	Analysis of the Coupling Mechanism between Airborne MEMS Ultrasonic Transducers and Ultrasonic Horns	303
	Gabriele Bosetti, Stefan Hofstetter-Spona and Gabriele Schrag	
P2.9G	Towards Integrated 3D Microbatteries: Study of LiPON on Porous Electrodes.....	885
	Julia Cipo1, Rahel-Manuela Neubieser, Reinhard Mörtel, Thomas Lisee, Marvin Michel and Fabian Lofink and Björn Gojdka	

A6 Prozesstechnologien (2)

Chair: Martin Hoffmann (Ruhr-Universität Bochum)

A6.1	Development of a process technology for the local generation of high temperatures in monocrystalline silicon	770
	Michel Müller, Heinrich Grüger, Thomas Graßhoff and Wolf-Dietrich Owe	
A6.2	Electro-optical co-integration platform for high-density hybrid systems - SILHOUETTE.....	774
	David Weyers, Mircea-Traian Cătuneanu, Margarita Lapteva, Vinya Vibhuti, Menglong He, Sascha Bönhardt, Matthias Landwehr, Johann Fell, Krzysztof Niewegłowski, Kambiz Jamshidi and Karlheinz Bock	
A6.3	Replikative Herstellung von Metallformen für die Polymerreplikation mit geringer Oberflächenrauigkeit	782
	Sebastian Kluck, Leonhard Hambitzer, Manuel Luitz, Markus Mader, Mario Sanjaya, Andreas Balster, Frederik Kotz-Helmer und Bastian E. Rapp	
A6.4	Influence of a Novel Solid Thermal Isolation Approach for Thin-film Flow Sensors on Thermopile Sensitivity and Dynamic Response of a MEMS Flow Sensor	787
	Ole Behrmann, Thomas Lisee, Sophie Billat, Alfons Dehé and Björn Gojdka	
A6.5	Sputter deposition via double ring magnetrons; superior reactive and process control for high rate metal, oxide and nitride films	791
	Stephan Barth, Hagen Bartzsch and Jörg Neidhardt	

B6 Sensorik (2)

Chairs: Hoc Khiem Trieu (Technische Universität Hamburg)

- B6.1 Technologien mit hohem Aspektverhältnis für Vibrationssensoren mit großer Bandbreite, hoher Empfindlichkeit und geringem Rauschen..... 797**
Petra Kuenzel, Roman Forke, Karla Hiller, Uwe Schwarz, Roman Ziegenhardt, Sven Voigt, Sebastian Weidlich, Alexey Shaporin, Susann Hahn, Matthias Küchler and Harald Kuhn
- B6.2 Direct-Deposited Thin-film Strain Gauges for High-temperature Applications 802**
Rico Ottermann, Niklas Kyoushi and Marc Christopher Wurz
- B6.3 Integrated Ion-Sensitive Field-Effect Transistor Using CMOS-Based Technology 806**
Christopher Beale, Falah Al-Falahi, Eberhard Kurth, Christian Kunath, Patrick Bott and Olaf R. Hild
- B6.4 Continuous monitoring of the dynamic viscosity of bitumen with piezoelectric MEMS sensors 810**
S. Alasatri, M. Schneider, J. Mirwald, B. Hofko and U. Schmid
- B6.5 Development of a Thermal Flow Sensor Based on the Ensinger Microsystems Technology 814**
Sebastian Bengsch, André Bülau, Andrea Knöller, Volker Kible, Daniela Walter, David Helm, Simon Petillon, Wolfgang Eberhardt, Karl-Peter Fritz, Stefan Bur, Michael Werner, Christian Henne, Matthias Wochele

C6 Mikroaktoren

Chair: Roland Zengerle (Hahn-Schickard-Gesellschaft für angewandte Forschung e.V. und Albert-Ludwigs-Universität Freiburg)

- C6.1 Enhanced Bi-Directional SMA Actuation of Origami-Inspired Microstructures 820**
Lena Seigner, Vincent Gottwald, Lars Bumke, Eckhard Quandt and Manfred Kohl
- C6.2 Modelling, Manufacturing and Characterization of Electrostatic Actuators towards an Electrostatic Silicon MEMS-Micropump..... 825**
Daniel Anheuer, Henry Leistner, Brinda George, Siegfried Roehl, Martin Richter and Christoph Kutter
- C6.3 A Bistable Actuator Based on Antagonistic Buckling SMA Beams..... 833**
Xi Chen, Lars Bumke, Eckhard Quandt and Manfred Kohl
- C6.4 Cantilever Free Magnetic Actuation for Multistable Vertical Displacement 839**
Pascal M. Weber, Arwed Schütz, Tamara Bechtold and Ulrike Wallrabe
- C6.4 Verkippte Konstantkraft-Dreiecksfedern für weitauslenkende elektrostatische Aktoren 844**
Lisa Schmitt, Philip Schmitt und Martin Hoffmann

D6 Nachhaltigkeit als Chance und Wettbewerbsvorteil

Chair: Matthias Straub (microTEC Südwest e.V.)

- D6.1 Kompetenzzentrum für eine ressourcenbewusste Informations- und Kommunikationstechnik – Green ICT @ FMD**
Nils F. Nissen (Fraunhofer IZM, Germany)

D6.2 Grüne Elektronik aus Deutschland? Stand und Perspektiven

Janine Kleemann (VDI VDE Innovation und Technik GmbH, Germany); Jochen Kerbusch (Institut für Innovation und Technik (iit) in der VDI/VDE Innovation + Technik GmbH, Germany); Gregor Schwartz (VDI VDE IT, Germany)

D6.3 Der Weg zu mehr Nachhaltigkeit und Klimaneutralität

Roland Dörr (microTEC Südwest e.V.); Christine Neuy (microTEC Südwest e.V.)

D6.4 Energie- und Ressourcenbedarf der IKT in Deutschland bis 2035..... 856

Nils F. Nissen and Lutz Stobbe